



[illegible]

Form a copper layer overlying a patterned dielectric layer

Form a doped layer superjacent the copper layer

Thermally drive dopants from doped layer into copper layer

Fig. 3

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502

Form a copper layer overlying a patterned dielectric layer

504

Remove excess metal so as to form individual copper interconnect lines

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Implant dopants into at least the interconnect lines

Fig. 5

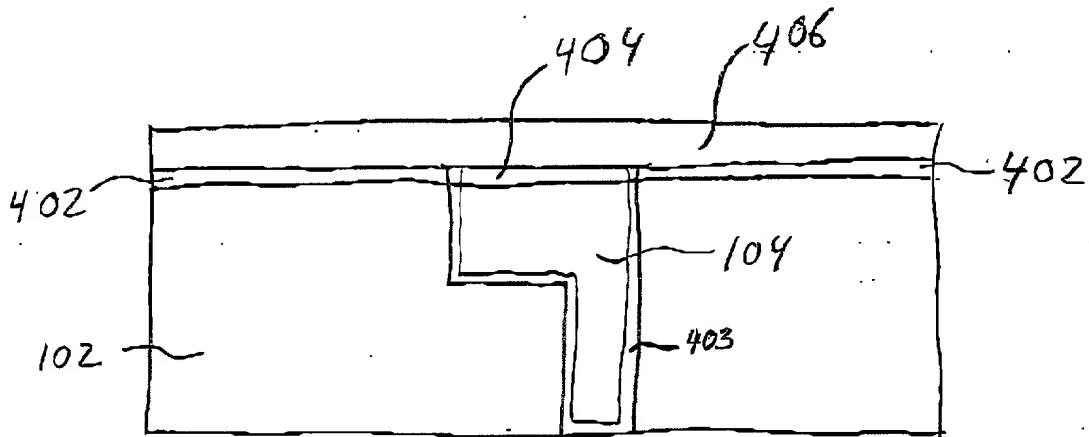


Fig. 4

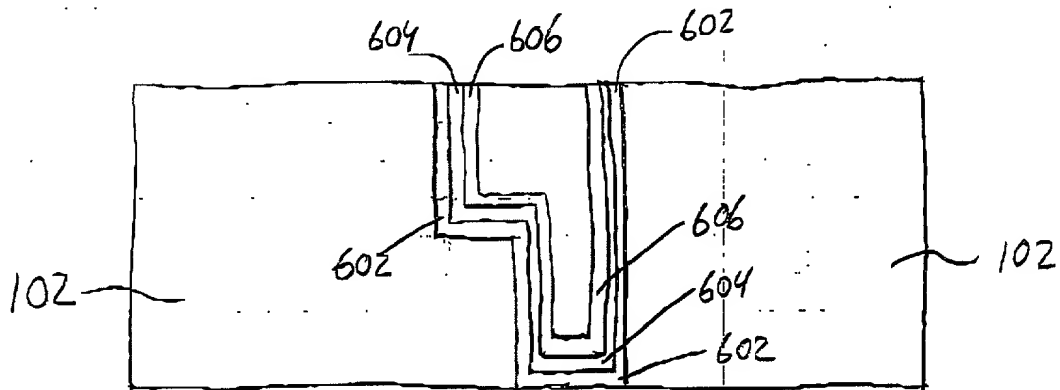


Fig. 6

09739929-121800

P10637

09739929-121800

702

704

706

708

Fig. 7

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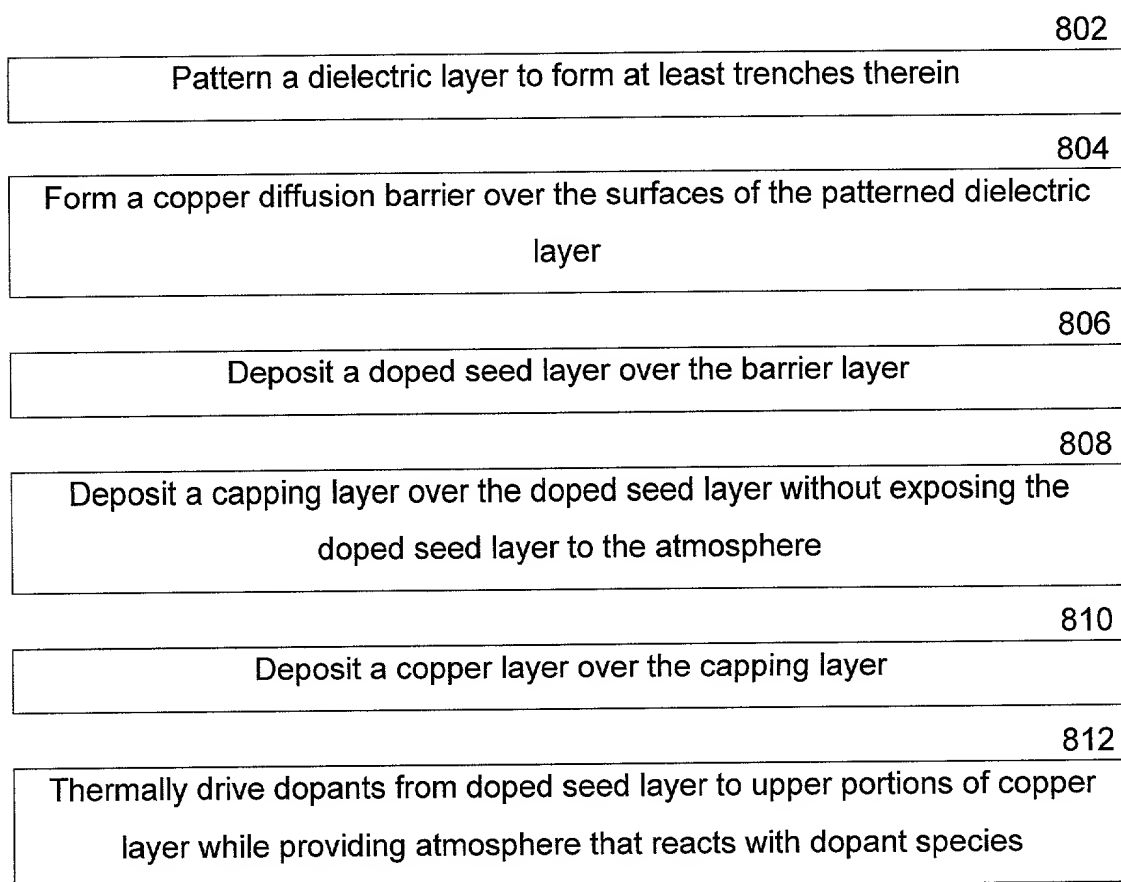


Fig. 8